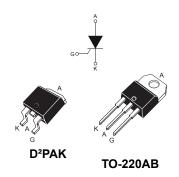


## High temperature 12 A SCRs



#### **Features**

- High junction temperature: T<sub>i</sub> = 150 °C
- Medium current SCRs
- High noise immunity up to 150 °C
- RoHS (2002/95/EC) compliant
- 600 V V<sub>DRM</sub>, V<sub>RRM</sub>

#### **Applications**

- · General purpose AC line load switching
- · Motor control circuits
- Small home appliances
- Lighting
- · Inrush current limiting circuits
- · Overvoltage crowbar protection

#### **Description**

lectronics sales office

Available in standard gate triggering levels, the TN1205H SCR series has very high switching capability up to a junction temperature of 150 °C.

These products fit all modes of control found in applications such as overvoltage crowbar protection, motor control circuits in power tools and kitchen aids, inrush current limiting circuits, capacitive discharge ignition and voltage regulation circuits.

These products are particulary adapted for use in areas where the ambient temperature is high or the ventilation low, or where an increase of power density is required.

Through-hole or surface-mount packages provide performance in a limited space area

# Product status link TN1205H

Product summary		
$V_{DRM}, V_{RRM}$	600 V	
I <sub>GT</sub>	2 to 5 mA	



## 1 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter	Value	Unit		
I <sub>T(RMS)</sub>	RMS on-state current (180° conduction angle))		T = 126 °C	12	_
I <sub>T(AV)</sub>	Average on-state current (180° conduction angle)	TO 220AP 1c = 130 C		7.6	Α
L	Non repetitive ourse peak on etete oursest	t <sub>p</sub> = 8.3 ms	T <sub>i</sub> = 25 °C	126	^
I <sub>TSM</sub>	Non repetitive surge peak on-state current	t <sub>p</sub> = 10 ms	1	120	A
l <sup>2</sup> t	I <sup>2</sup> t value for fusing	72	A <sup>2</sup> s		
dl/dt	Critical rate of rise of on-state current, $I_G = 2 \times I_{GT}$ , tr $\leq 100$ ns, F = 60 Hz $T_j = 150$ °C				A/µs
V <sub>DSM</sub> / V <sub>RSM</sub>	Non Repetitive peak off-state voltage $t_p = 10 \text{ ms}$				V
I <sub>GM</sub>	Peak gate current	t <sub>p</sub> = 20 μs	T <sub>j</sub> = 150 °C	4	Α
P <sub>G(AV)</sub>	Average gate power dissipation $T_j = 150  ^{\circ}\text{C}$				W
$V_{RGM}$	Maximum peak reverse gate voltage	5	V		
T <sub>stg</sub>	Storage temperature range	-40 to +150	°C		
Tj	Operating junction temperature range	-40 to +150	°C		
TL	Maximum lead temperature for soldering during 10 s.	260	°C		

Table 2. Electrical characteristics ( $T_j$  = 25 °C, unless otherwise specified)

Symbol	Test cond	Test conditions			
I <sub>GT</sub> <sup>(1)</sup>	1(1)		Max.	2	mA
'GT`	$V_D = 12 \text{ V}, R_L = 33 \Omega$			5	IIIA
V <sub>GT</sub>			Max.	1.3	V
V <sub>GD</sub>	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega$		Min.	0.2	V
IL	$I_{G} = 1.2 \times I_{GT}$			40	mA
I <sub>H</sub> (2)	I <sub>T</sub> = 500 mA, gate open		Max.	20	mA
dV/dt (2)	$V_D = 67\% V_{DRM}$ , gate open	T <sub>j</sub> = 125 °C	N.A.	200	V/µs
av/at (2)	v <sub>D</sub> = 07 % v <sub>DRM</sub> , gate open	T <sub>j</sub> = 150 °C	Min.	100	
t <sub>gt</sub>	I <sub>TM</sub> = 40 A, V <sub>D</sub> = 500 V, I <sub>G</sub> = 100 mA, dI <sub>G</sub> /dt = 5 A/μs			1.9	μs
tq	$V_{DM}$ = 335 V, $T_j$ =125 °C, $I_{TM}$ = 20 A, $V_R$ = 25 V, $(dI_T/dt)_{Max}$ = 30 A/µs, $dV_D/dt$ = 50 V/µs, $R_{GK}$ = 100 $\Omega$			65	μs

<sup>1.</sup> Minimum  $I_{GT}$  is guaranteed at 20% of  $I_{GT}$  max.

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<sup>2.</sup> For both polarities of A2 referenced to A1.



#### **Table 3. Static characteristics**

Symbol	Test conditions	Max. value	Unit	
V <sub>T</sub>	$I_{TM}$ = 24 A, $t_p$ = 380 $\mu s$	T <sub>j</sub> = 25 °C	1.6	V
V <sub>TD</sub>	Threshold voltage	T <sub>j</sub> = 150 °C	0.80	V
R <sub>D</sub>	Dynamic resistance	T <sub>j</sub> = 150 °C	30	mΩ
		T <sub>j</sub> = 25 °C	5	μΑ
I <sub>DRM</sub> /I <sub>RRM</sub>	$V_{DRM} = V_{RRM}$	T <sub>j</sub> = 125°C	1	mA
		T <sub>j</sub> = 150 °C	3	mA

#### **Table 4. Thermal resistance**

Symbol	Parameter	Value	Unit	
R <sub>th(j-c)</sub>	Junction to case (DC)	1.3	°C/W	
R <sub>th(j-a)</sub> J	Junation to ambient DC (S = 1 am²)	D²PAK	45	°C/W
	Junction to ambient DC (S <sub>cu</sub> = 1 cm <sup>2</sup> )	TO-220AB	60	C/VV

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5

3 2

#### 1.1 Characteristics curves

Figure 1. Maximum power dissipation versus on-state RMS current

Figure 3. Average and DC on-state current versus ambient temperature

5

3

 $I_{T(AV)}(A)$ 

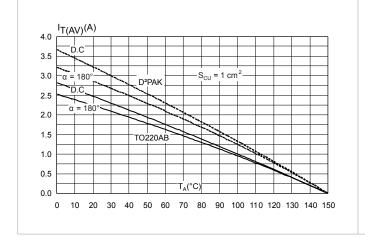
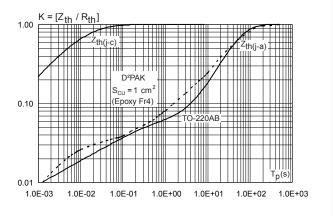


Figure 4. Variation of thermal impedance versus pulse duration



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Figure 5. Relative variation of  $I_{GT}$ ,  $V_{GT}$ ,  $I_{H}$ ,  $I_{L}$  versus junction temperature (typical values)

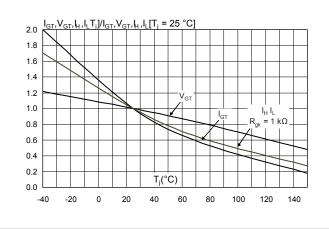


Figure 6. Relative variation of static dV/dt immunity versus junction temperature (typical values)

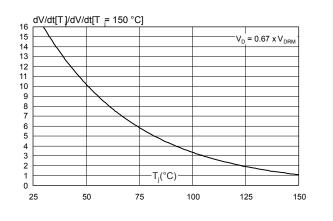


Figure 7. Surge peak on-state current versus number of cycles

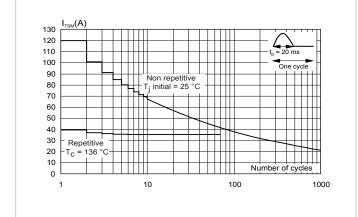
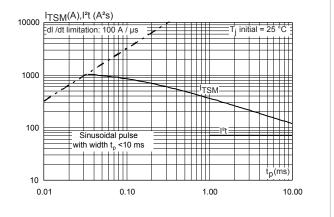
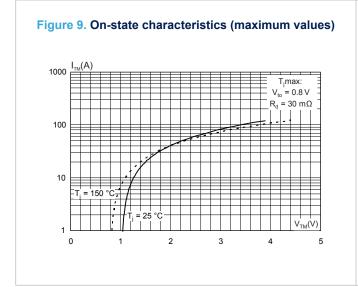


Figure 8. Non repetitive surge peak on-state current and corresponding value of l²t versus sinusoidal pulse width



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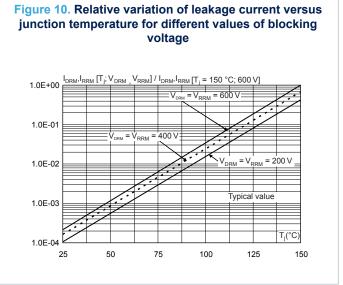
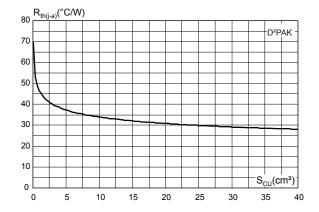


Figure 11. Thermal resistance junction to ambient versus copper surface under tab (D $^2$ PAK, printed circuit board FR4, copper thickness: 35  $\mu$ m)



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## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

#### 2.1 D<sup>2</sup>PAK package information

- ECOPACK2 compliant
- · Lead-free package leads finishing
- Molding compound resin is halogen-free and meets UL94 flammability standard level V0

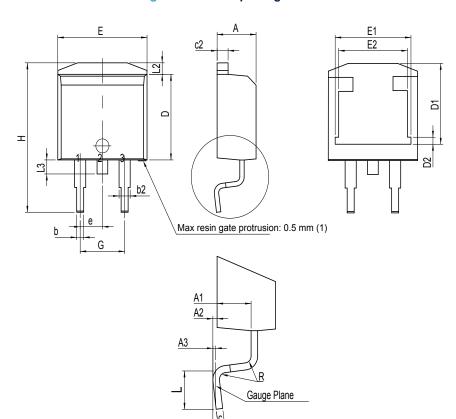


Figure 12. D<sup>2</sup>PAK package outline

(1) Resin gate is accepted in each of position shown on the drawing, or their symmetrical.

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Table 5. D<sup>2</sup>PAK package mechanical data

	Dimensions						
Ref.		Millimeters			Inches <sup>(1)</sup>		
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	4.30		4.60	0.1693		0.1811	
A1	2.49		2.69	0.0980		0.1059	
A2	0.03		0.23	0.0012		0.0091	
A3		0.25			0.0098		
b	0.70		0.93	0.0276		0.0366	
b2	1.25		1.7	0.0492		0.0669	
С	0.45		0.60	0.0177		0.0236	
c2	1.21		1.36	0.0476		0.0535	
D	8.95		9.35	0.3524		0.3681	
D1	7.50		8.00	0.2953		0.3150	
D2	1.30		1.70	0.0512		0.0669	
е	2.54			0.10000			
E	10.00		10.28	0.3937		0.4047	
E1	8.30		8.70	0.3268		0.3425	
E2	6.85		7.25	0.2697		0.2854	
G	4.88		5.28	0.1921		0.2079	
Н	15		15.85	0.5906		0.6240	
L	1.78		2.28	0.0701		0.0898	
L2	1.19		1.40	0.0460		0.0551	
L3	1.40		1.75	0.0551		0.0689	
R		0.40			0.0157		
V2 <sup>(2)</sup>	0°		8°	0°		8°	

<sup>1.</sup> Dimensions in inches are given for reference only

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<sup>2.</sup> Degrees





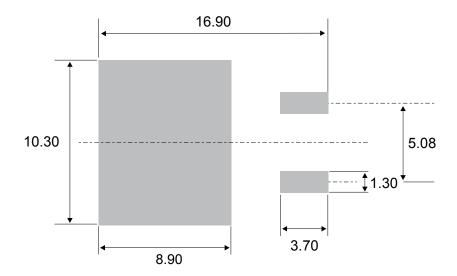
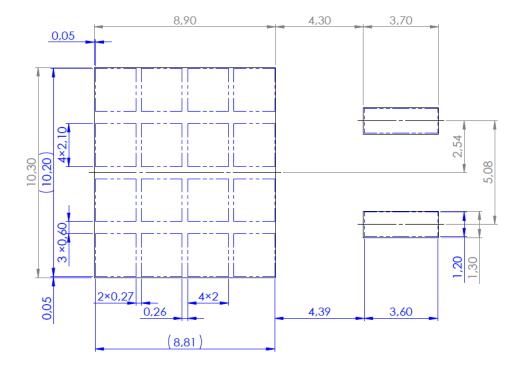


Figure 14. D<sup>2</sup>PAK stencil definitions (dimensions are in mm)



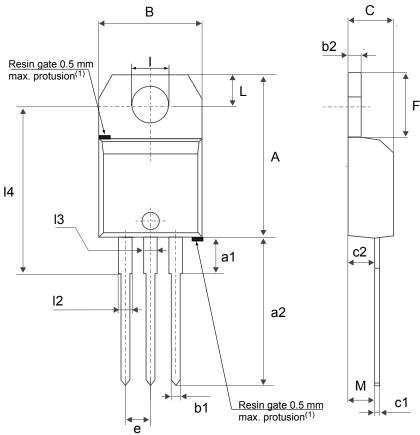
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### 2.2 TO-220AB package information

- Molding compound resin is halogen-free and meets flammability standard UL94 level 0
- · Lead-free package leads finishing
- ECOPACK2 compliant
- Recommended torque: 0.4 to 0.6 N.m

Figure 15. TO-220AB package outline



(1)Resin gate position accepted in one of the two positions or in the symmetrical opposites.

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Table 6. TO-220AB package mechanical data

	Dimensions						
Ref.		Millimeters			Inches <sup>(1)</sup>		
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	15.20		15.90	0.5984		0.6260	
a1		3.75			0.1476		
a2	13.00		14.00	0.5118		0.5512	
В	10.00		10.40	0.3937		0.4094	
b1	0.61		0.88	0.0240		0.0346	
b2	1.23		1.32	0.0484		0.0520	
С	4.40		4.60	0.1732		0.1811	
c1	0.49		0.70	0.0193		0.0276	
c2	2.40		2.72	0.0945		0.1071	
е	2.40		2.70	0.0945		0.1063	
F	6.20		6.60	0.2441		0.2598	
ı	3.73		3.88	0.1469		0.1528	
L	2.65		2.95	0.1043		0.1161	
12	1.14		1.70	0.0449		0.0669	
13	1.14		1.70	0.0449		0.0669	
14	15.80	16.40	16.80	0.6220	0.6457	0.6614	
M		2.6			0.1024		

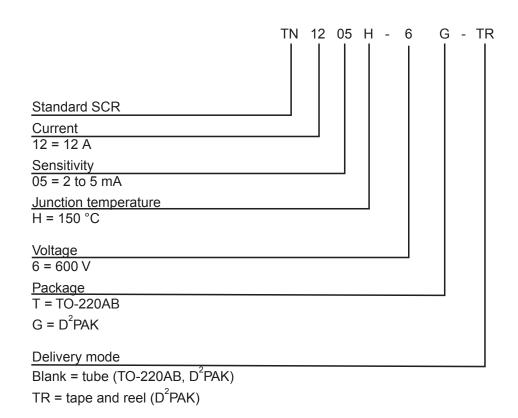
<sup>1.</sup> Inch dimensions are for reference only.

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# 3 Ordering information

Figure 16. Ordering information scheme



**Table 7. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
TN1205H-6T	TN1205H6T	TO-220AB	2.0 g	50	Tube
TN1205H-6G	TN1205H6G	D²PAK	1.5 g	50	Tube
TN1205H-6G-TR	TN1205H6G	D²PAK	1.5 g	1000	Tape and reel

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# **Revision history**

**Table 8. Document revision history** 

Date	Version	Changes
17-Feb-2011	1	First issue.
26-Sep-2011	2	Corrected typographical error in Features and Description.
17-Jan-2012	3	Updated units for tgt in Table 3.
26-Apr-2012	4	Moved junction temperature to top of features list.  Description reworded for readability. No technical changes.
24-Sep-2020	5	Updated Table 2. Electrical characteristics ( $T_j$ = 25 °C, unless otherwise specified).



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